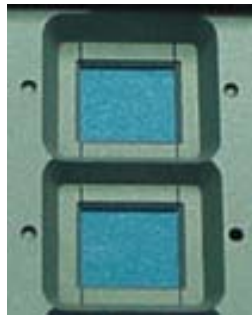


HEATER BLOCKS

SPT's Heater Block Assembly offers yet another value-added product to further support end-users for their complex bonding application. SPT is capable to fabricate a wide variety of heater block assembly for all types of packages used on any type of wire bonder.

SPT's "butterfly" design has proven to eliminate the bouncing effect on the lead finger. The "butterfly" design has shown excellent gripping & clamping stability on lead fingers, especially for high pin counts QFP packages. With SPT's "butterfly" design, no high temperature tape is required. This has been tested and proven at many customer production sites with superior performance as compared to conventional design.



Top View "Butterfly" Design



Bottom View "Butterfly" Design

Advantages:

- Absolute lead finger stability during bonding with the "butterfly" design heater block assembly.
- The "butterfly" heater block assembly can be applied to a wide range of lead frame design for all types of wire bonder.
- Especially useful for FP and UFP high pin count devices.

How To Order:

HBXX - User Code - Bonder Model - Package Type (Batch Number)

HBXX: Part Type + Bonding Window Quantity

HB: order both clamp and heater block

HBC: order clamp only

HBH: order heater block only

Example :- HB4X - Semicon - ASM 339 - QFP208L (A123)

SHINKAWA BONDER	ESEC Bonder	ASM Bonder
KNS BONDER	SHINKAWA SDW 35 BONDER	OE360 BONDER FINGER CLAMP